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Concl'd

"Complaint, Solderable Input/Output Bump Structures,"
Serial No. 09/501,177, co-filed herewith.

In the Claims:

Add the following new claim 41:

41. (New) A structure for absorbing stress between a first electrical structure and a second electrical structure, said structure comprising:

a dielectric material disposed on at least one of said first electrical structure and said second electrical structure;

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wherein said dielectric material comprises a low modulus material which has a high ultimate elongation property, and wherein said dielectric comprises a low modulus high elongation (LMHE) dielectric which functions to absorb stress between said first and second electrical structures resulting from said first and second electrical structures having different coefficients of thermal expansion; and

wherein said LMHE dielectric has a Young's modulus of less than 50,000 psi, and has an ultimate elongation property of at least twenty percent.